

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

in re Application of: Agarwal et al.

Application No. 10/002,779

Filed: October 29, 2001

For: METHODS FOR FORMING AND

INTEGRATED CIRCUIT STRUCTURES

CONTAINING RUTHENIUM AND TUNGSTEN

CONTAINING LAYERS

Examiner: David Vu

Date: August 14, 2003

MAIL STOP RCE COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450 CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on August 14, 2003 as First Class Mail in an envelope addressed to: MAIL STOP RCE, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA

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Attorney for Applicant

Art Unit: 2818

AMENDMENT

This responds to the Office action dated March 14, 2003. Prior to continued examination, please amend the referenced application as follows:

Amendments to the Claims are reflected in the listing of claims, which begins on page 2.

Remarks begin on page 4.